

PART INFORMATION

Mfg Item Number	MPC565CZP56
Mfg Item Name	PBGA 388 27*27*1.25P1.0

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2015-03-19
Response Document ID	5254K00033D060A1.35
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
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Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION

EU RoHS	No
Pb Free	No
HalogenFree	No
Plating Indicator	e0
EU RoHS Exemption(s)	

MANUFACTURING

Mfg Item Number	MPC565CZP56
Mfg Item Name	PBGA 388 27*27*1.25P1.0
Version	ALL
Weight	2.450850
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	240 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Epoxy Die Attach	0.0188						g				
Epoxy Die Attach		Solvents, additives, and other materials	1,3,5-Triazine-2,4-diamine, 6-[2-(2-methyl-1H-imidazol-1-yl)ethyl]	38668-46-1		0.00015888	g	8451	0.8451	64	0.0064
Epoxy Die Attach		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.00243609	g	129579	12.9579	983	0.0983
Epoxy Die Attach		Plastics/polymers	4,4'-Dihydroxydiphenyl	92-88-6		0.00015888	g	8451	0.8451	64	0.0064
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.01604615	g	853519	85.3519	6547	0.6547
Die Encapsulant	1.16025						g				
Die Encapsulant		Antimony/Arsimony Compounds	Antimony trioxide	1309-64-4		0.00767694	g	6789	0.6789	3213	0.3213
Die Encapsulant		Lead/Lead Compounds	Lead	7439-92-1		0.0000116	g	10	0.001	4	0.0004
Die Encapsulant		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.01575503	g	13570	1.3570	6426	0.6426
Die Encapsulant		Plastics/polymers	Proprietary Material-Other phenolic resins	-		0.05626864	g	48497	4.8497	22958	2.2958
Die Encapsulant		Plastics/polymers	Proprietary Material-Other polymers	-		0.11253497	g	96992	9.6992	45916	4.5916
Die Encapsulant		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.96684839	g	824433	82.4433	390307	39.0307
Die Encapsulant		Plastics/polymers	Other brominated epoxy resins	-		0.01125443	g	9700	0.97	4592	0.4592
Solder Balls - Low Lead	0.3646						g				
Solder Balls - Low Lead		Lead/Lead Compounds	Lead	7439-92-1		0.131256	g	360000	36	53555	5.3555
Solder Balls - Low Lead		Metals	Silver, metal	7440-22-4		0.007292	g	20000	2	2975	0.2975
Solder Balls - Low Lead		Metals	Tin, metal	7440-31-5		0.226062	g	620000	62	92234	9.2234
Silicon Semiconductor Die	0.051						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.00102	g	20000	2	416	0.0416
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.04998	g	980000	98	20392	2.0392
Organic Substrate	0.8333						g				
Organic Substrate		Metals	Barium	7440-39-3		0.03903261	g	46841	4.6841	15926	1.5926
Organic Substrate		Flame Retardants	Bromophenol, formaldehyde, epichlorohydrin polymer	68541-56-0		0.0001189	g	106147	10.6147	36770	3.677
Organic Substrate		Metals	Copper, metal	7440-50-8		0.14869989	g	178447	17.8447	60672	6.0672
Organic Substrate		Plastics/polymers	2,2'-(1-methylethylene)bis(4,1-phenyleneoxymethylene)bisoxirane	1675-54-3		0.00209825	g	2518	0.2518	856	0.0856
Organic Substrate		Plastics/polymers	Poly[o-cresyl glycidyl ether]-co-formaldehyde	26890-82-2		0.03918177	g	47020	4.702	15987	1.5987
Organic Substrate		Metals	Gold, metal	7440-57-5		0.00143161	g	1718	0.1718	584	0.0584
Organic Substrate		Solvents, additives, and other materials	1,1'-(methylene)di-p-phenylene)bisoxirane	13676-54-5		0.07836437	g	94041	9.4041	31974	3.1974
Organic Substrate		Nickel (external applications only)	Nickel	7440-02-0		0.00847716	g	10173	1.0173	3458	0.3458
Organic Substrate		Plastics/polymers	4,4'-isopropylidenediphenol-1-chloro-2,3-epoxypropane bisacrylate	25068-38-6		0.03918177	g	47020	4.702	15987	1.5987
Organic Substrate		Glass	Fibero-glass-wool	65997-17-3		0.31148564	g	373810	37.381	127097	12.7097
Organic Substrate		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.00118029	g	1426	0.1426	484	0.0484
Organic Substrate		Solvents, additives, and other materials	Proprietary Material-Other miscellaneous substances.	-		0.01123705	g	13485	1.3485	4584	0.4584
Organic Substrate		Plastics/polymers	Other Non-halogenated Epoxy resins	-		0.06279249	g	75354	7.5354	25620	2.562
Bonding Wire	0.0229						g				
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0229	g	1000000	100	9343	0.9343

LINKS

MCD LINK

Freescale website <http://www.freescale.com>

GENERAL ENVIRONMENTAL COMPLIANCE LINKS

RoHS signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf

China RoHS <http://www.freescale.com/chinarohs>

REACH signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf

ELV signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf

Conflict Minerals statement http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf

FREESCALE ENVIRONMENTAL INFORMATION

EPP website <http://www.freescale.com/epp>

FAQ http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ

Technical Service Request https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod

LINKS TO BLANK IPC1752 FORMS

Blank IPC1752 v1.1 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/MPC565CZP56_IPC1752_v11.xml

http://www.freescale.com/mcdfs/MPC565CZP56_IPC1752A.xml